

Sergey K Tolpygo

List of Publications by Year in descending order

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Version: 2024-02-01

30
papers

1,065
citations

586496

16
h-index

536525

29
g-index

30
all docs

30
docs citations

30
times ranked

614
citing authors

#	ARTICLE	IF	CITATIONS
1	A New Family of bioSFQ Logic/Memory Cells. IEEE Transactions on Applied Superconductivity, 2022, 32, 1-5.	1.1	14
2	Mutual and Self-Inductance in Planarized Multilayered Superconductor Integrated Circuits: Microstrips, Striplines, Bends, Meanders, Ground Plane Perforations. IEEE Transactions on Applied Superconductivity, 2022, 32, 1-31.	1.1	9
3	Wafer-Scale Characterization of a Superconductor Integrated Circuit Fabrication Process, Using a Cryogenic Wafer Prober. IEEE Transactions on Applied Superconductivity, 2022, 32, 1-12.	1.1	2
4	Inductance of superconductor integrated circuit features with sizes down to 120 nm. Superconductor Science and Technology, 2021, 34, 085005.	1.8	18
5	SFQ Bias for SFQ Digital Circuits. IEEE Transactions on Applied Superconductivity, 2021, 31, 1-7.	1.1	7
6	Increasing integration scale of superconductor electronics beyond one million Josephson junctions. Journal of Physics: Conference Series, 2020, 1559, 012002.	0.3	20
7	Planarized Fabrication Process With Two Layers of SIS Josephson Junctions and Integration of SIS and SFS <i>Junctions. IEEE Transactions on Applied Superconductivity, 2019, 29, 1-8.	1.1	14
8	Advanced Fabrication Processes for Superconductor Electronics: Current Status and New Developments. IEEE Transactions on Applied Superconductivity, 2019, 29, 1-13.	1.1	64
9	Reliability Studies of Nb/AlO _x /Al/Nb Josephson Junctions Through Accelerated-Life Electrical Stress Testing. IEEE Transactions on Applied Superconductivity, 2019, 29, 1-7.	1.1	1
10	Very Large Scale Integration of Josephson-Junction-Based Superconductor Random Access Memories. IEEE Transactions on Applied Superconductivity, 2019, 29, 1-9.	1.1	34
11	Superconductor Electronics Fabrication Process with MoN _x Kinetic Inductors and Self-Shunted Josephson Junctions. IEEE Transactions on Applied Superconductivity, 2018, 28, 1-12.	1.1	42
12	Submicron Nb Microwave Transmission Lines and Components for Single-Flux-Quantum and Analog Large-Scale Superconducting Integrated Circuits. IEEE Transactions on Applied Superconductivity, 2017, 27, 1-5.	1.1	8
13	AC-Biased Shift Registers as Fabrication Process Benchmark Circuits and Flux Trapping Diagnostic Tool. IEEE Transactions on Applied Superconductivity, 2017, 27, 1-9.	1.1	38
14	Properties of Unshunted and Resistively Shunted Nb/AlO _x /Al/Nb Josephson Junctions With Critical Current Densities From 0.1 to 1 mA/μm ² . IEEE Transactions on Applied Superconductivity, 2017, 27, 1-15.	1.1	60
15	Developments toward a 250-nm, Fully Planarized Fabrication Process with Ten Superconducting Layers and Self-Shunted Josephson Junctions. , 2017, , .		14
16	Superconductor digital electronics: Scalability and energy efficiency issues (Review Article). Low Temperature Physics, 2016, 42, 361-379.	0.2	143
17	Advanced Fabrication Processes for Superconducting Very Large Scale Integrated Circuits. IEEE Transactions on Applied Superconductivity, 2016, , 1-1.	1.1	175
18	Inductance of Circuit Structures for MIT LL Superconductor Electronics Fabrication Process With 8 Niobium Layers. IEEE Transactions on Applied Superconductivity, 2015, 25, 1-5.	1.1	60

#	ARTICLE	IF	CITATIONS
19	New AC-Powered SFQ Digital Circuits. IEEE Transactions on Applied Superconductivity, 2015, 25, 1-7.	1.1	43
20	Fabrication Process and Properties of Fully-Planarized Deep-Submicron Nb/Al \times Josephson Junctions for VLSI Circuits. IEEE Transactions on Applied Superconductivity, 2015, 25, 1-12.	1.1	113
21	Deep sub-micron stud-via technology of superconductor VLSI circuits. Superconductor Science and Technology, 2014, 27, 025016.	1.8	29
22	Diffusion Stop-Layers for Superconducting Integrated Circuits and Qubits With Nb-Based Josephson Junctions. IEEE Transactions on Applied Superconductivity, 2011, 21, 119-125.	1.1	13
23	Investigation of the Role of H in Fabrication-Process- Induced Variations of $\text{Nb/Al}_x\text{/Nb}$ Josephson Junctions. IEEE Transactions on Applied Superconductivity, 2011, 21, 126-130.	1.1	9
24	3D Active Demagnetization of Cold Magnetic Shields. IEEE Transactions on Applied Superconductivity, 2011, 21, 724-727.	1.1	9
25	Effect of Electrical Stress on Josephson Tunneling Characteristics of $\text{Nb/Al}_x\text{/Nb}$ Junctions. IEEE Transactions on Applied Superconductivity, 2009, 19, 154-158.	1.1	5
26	Wafer Bumping Process and Inter-Chip Connections for Ultra-High Data Transfer Rates in Multi-Chip Modules With Superconductor Integrated Circuits. IEEE Transactions on Applied Superconductivity, 2009, 19, 598-602.	1.1	9
27	Process-Induced Variability of $\text{Nb/Al}_x\text{/Nb}$ Junctions in Superconductor Integrated Circuits and Protection Against It. IEEE Transactions on Applied Superconductivity, 2009, 19, 135-139.	1.1	8
28	Electrical stress effect on Josephson tunneling through ultrathin AlO _x barrier in Nb/Al/AlO _x /Nb junctions. Journal of Applied Physics, 2008, 104, .	1.1	19
29	Plasma process-induced damage to Josephson tunnel junctions in superconducting integrated circuits. Superconductor Science and Technology, 2007, 20, S341-S349.	1.8	24
30	20 kA/cm^2 Process Development for Superconducting Integrated Circuits With 80 GHz Clock Frequency. IEEE Transactions on Applied Superconductivity, 2007, 17, 946-951.	1.1	61